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## Product Change Notification - KSRA-16BWET454 (Printer Friendly)

### Date:

18 Jul 2017

### Product Category:

16-Bit - Microcontrollers and Digital Signal Controllers; Capacitive Touch Sensors; 32-bit PIC Microcontrollers

### Notification subject:

CCB 3027 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 0.18um TSMC wafer technology available in 44L QFN package at NSEB assembly

### Notification text:

#### PCN Status:

Initial notification

### Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPEN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

### Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18um TSMC wafer technology available in 44L QFN package at NSEB assembly site

### Pre Change:

Using gold (Au) bond wire

### Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire

### Pre and Post Change Summary:

	Pre Change	Post Change
<b>Assembly Site</b>	NSEB Assembly Site	NSEB Assembly Site
<b>Wire material</b>	Au Wire	CuPdAu Wire
<b>Die attach material</b>	8600	8600

<b>Molding compound material</b>	G700LTD	G700LTD
<b>Lead frame material</b>	C194	C194

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

**Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date:**

January 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

Workweek	July 2017						-->	January 2018				
	26	27	28	29	30	31		01	02	03	04	05
Initial PCN Issue Date				X								
Qual Report Availability								X				
Final PCN Issue Date								X				

**Method to Identify Change:**

Traceability code

**Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan

**Revision History:**

**July 18, 2017:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_KSRA-16BWET454\\_Affected CPN.pdf](#)

[PCN\\_KSRA-16BWET454\\_Qual Plan.pdf](#)

[PCN\\_KSRA-16BWET454\\_Affected CPN.xlsx](#)

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